

Title (en)  
PROCESS FOR REFLOW SOLDERING OF CIRCUIT BOARDS FITTED WITH SMD COMPONENTS

Title (de)  
VERFAHREN ZUM REFLOWLÖTEN VON MIT SMD-BAUELEMENTEN BESTÜCKTEN LEITERPLATTEN

Title (fr)  
PROCEDE DE SOUDAGE PAR REFUSION DE PLAQUETTES DE CIRCUITS IMPRIMES EQUIPEES DE COMPOSANTS MONTES EN SURFACE

Publication  
**EP 0903061 A1 19990324 (DE)**

Application  
**EP 97943748 A 19970909**

Priority

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- DE 19651862 A 19961213

Abstract (en)  
[origin: DE19651862A1] This invention concerns a process for reflow soldering of circuit boards fitted SMD components in which SMD components are placed on soldering surfaces of the first side of a circuit board and soldered to the circuit board in a first reflow soldering step. Subsequently the circuit board is turned with the first side underneath and SMD components are placed on soldering surfaces of the upward-facing second side, which are soldered to the circuit board in a subsequent reflow soldering step. The SMD components on the first side of the circuit board are firmly cemented to the circuit board before the second reflow soldering step on the first side. It is proposed that after the first reflow soldering step a cement be injected from the second side of the circuit board through holes which pass through the circuit board and correspond to the components soldered to the first side of the board into the space between the components and circuit board.

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IPC 8 full level  
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Citation (search report)  
See references of WO 9826638A1

Cited by  
CN101827501A

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